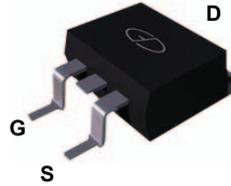
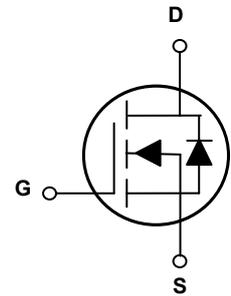


## Main Product Characteristics

|              |               |
|--------------|---------------|
| $V_{DSS}$    | 150V          |
| $R_{DS(on)}$ | 7.2m $\Omega$ |
| $I_D$        | 140A          |



TO-263 (D<sup>2</sup>PAK)



Schematic Diagram

## Features and Benefits

- Excellent gate charge
- Low R<sub>ds(on)</sub>
- Ideal for high-frequency switching
- Low conduction and switching power loss



## Description

The GSGT15140 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

| Parameter   | Symbol                   | Value      | Unit |
|---|--------------------------|------------|------|
| Drain-Source Voltage                              | $V_{DS}$                 | 150        | V    |
| Gate-Source Voltage                               | $V_{GS}$                 | ±20        | V    |
| Drain Current-Continuous                          | $I_D$                    | 140        | A    |
| Drain Current-Continuous(T <sub>C</sub> =100°C)   | $I_D(100^\circ\text{C})$ | 100        | A    |
| Pulsed Drain Current <sup>1</sup>                 | $I_{DM}$                 | 560        | A    |
| Maximum Power Dissipation                         | $P_D$                    | 320        | W    |
| Derating Factor                                   |                          | 2.1        | W/°C |
| Single pulse avalanche energy <sup>5</sup>        | $E_{AS}$                 | 1296       | mJ   |
| Operating Junction and Storage Temperature Range  | $T_J, T_{STG}$           | -55 To 175 | °C   |
| Thermal Resistance, Junction-to-Case <sup>2</sup> | $R_{\theta JC}$          | 0.47       | °C/W |

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

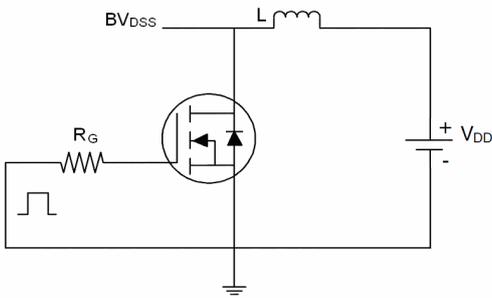
| Parameter                                     | Symbol       | Condition   | Min | Typ  | Max       | Unit       |
|---|--------------|---|-----|------|-----------|------------|
| <b>Off Characteristics</b>                    |              |   |     |      |           |            |
| Drain-Source Breakdown Voltage                | $BV_{DSS}$   | $V_{GS}=0V, I_D=250\mu A$                                     | 150 | 155  | -         | V          |
| Zero Gate Voltage Drain Current               | $I_{DSS}$    | $V_{DS}=150V, V_{GS}=0V$                                      |     | -    | 1         | $\mu A$    |
| Gate-Body Leakage Current                     | $I_{GSS}$    | $V_{GS}=\pm 20V, V_{DS}=0V$                                   |     | -    | $\pm 100$ | nA         |
| <b>On Characteristics</b> <sup>3</sup>        |              |   |     |      |           |            |
| Gate Threshold Voltage                        | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$                                 | 2.0 | 3.3  | 4.0       | V          |
| Drain-Source On-State Resistance              | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=70A$   |     | 6    | 7.2       | m $\Omega$ |
| Forward Transconductance                      | $g_{FS}$     | $V_{DS}=10V, I_D=70A$   |     | -    | -         | S          |
| <b>Dynamic Characteristics</b> <sup>4</sup>   |              |   |     |      |           |            |
| Input Capacitance                             | $C_{iss}$    | $V_{DS}=75V, V_{GS}=0V,$<br>$F=1.0\text{MHz}$                 | -   | 5500 | -         | PF         |
| Output Capacitance                            | $C_{oss}$    |   | -   | 600  | -         | PF         |
| Reverse Transfer Capacitance                  | $C_{rss}$    |   | -   | 7    | -         | PF         |
| <b>Switching Characteristics</b> <sup>4</sup> |              |   |     |      |           |            |
| Turn-on Delay Time                            | $t_{d(on)}$  | $V_{DD}=75V, I_D=70A$<br>$V_{GS}=10V, R_G=4.7\Omega$          | -   | 26   | -         | nS         |
| Turn-on Rise Time                             | $t_r$        |   | -   | 36   | -         | nS         |
| Turn-Off Delay Time                           | $t_{d(off)}$ |   | -   | 47   | -         | nS         |
| Turn-Off Fall Time                            | $t_f$        |   | -   | 15   | -         | nS         |
| Total Gate Charge                             | $Q_g$        | $V_{DS}=75V, I_D=70A,$<br>$V_{GS}=10V$                        | -   | 74   |           | nC         |
| Gate-Source Charge                            | $Q_{gs}$     |   | -   | 32   |           | nC         |
| Gate-Drain Charge                             | $Q_{gd}$     |   | -   | 11   |           | nC         |
| <b>Drain-Source Diode Characteristics</b>     |              |   |     |      |           |            |
| Diode Forward Voltage <sup>3</sup>            | $V_{SD}$     | $V_{GS}=0V, I_F=I_S$  | -   |      | 1.2       | V          |
| Diode Forward Current <sup>2</sup>            | $I_S$        |   | -   | -    | 140       | A          |
| Reverse Recovery Time                         | $t_{rr}$     | $T_J = 25^\circ\text{C}, I_F = I_S$<br>$di/dt = 100A/\mu s^3$ |     | 146  |           | nS         |
| Reverse Recovery Charge                       | $Q_{rr}$     |   | -   | 485  |           | nC         |

**Notes:**

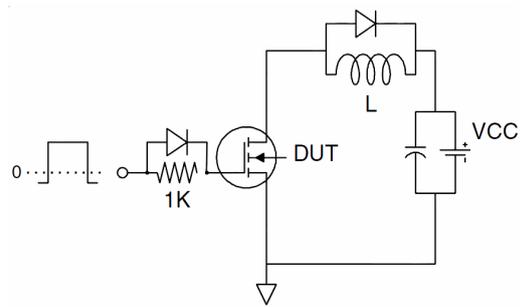
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed only by design.
5. EAS condition :  $T_J=25^\circ\text{C}, V_{DD}=50V, V_G=10V, L=0.5\text{mH}, R_G=25\Omega$

**Test Circuits and Waveforms**

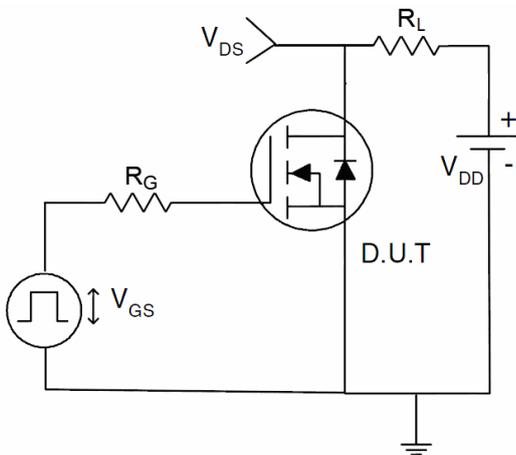
**EAS Test Circuit:**



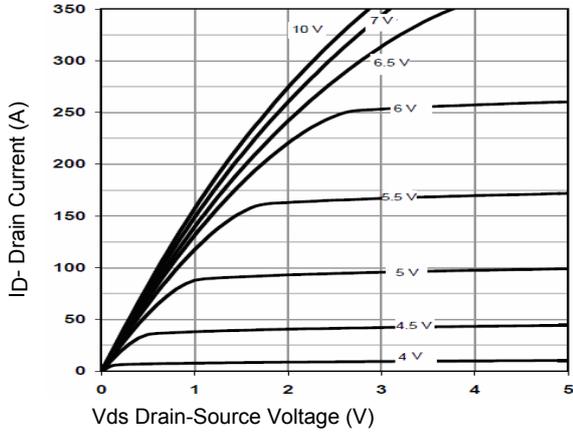
**Gate charge test circuit:**



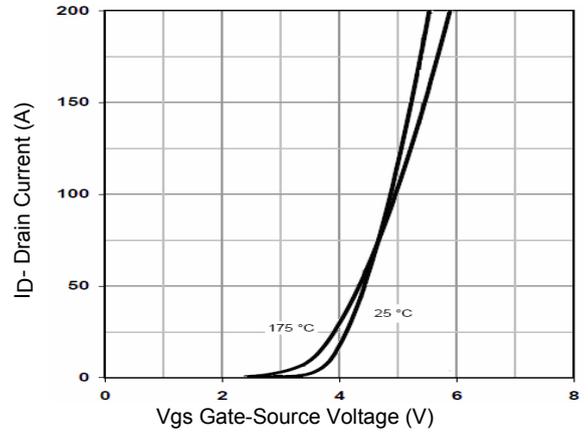
**Switching Time Test Circuit:**



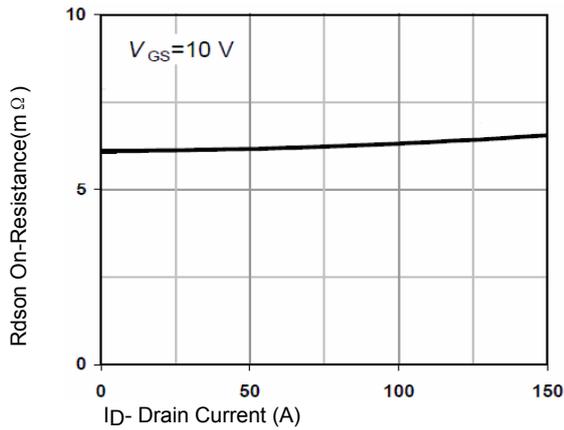
**Typical Electrical and Thermal Characteristic Curves**



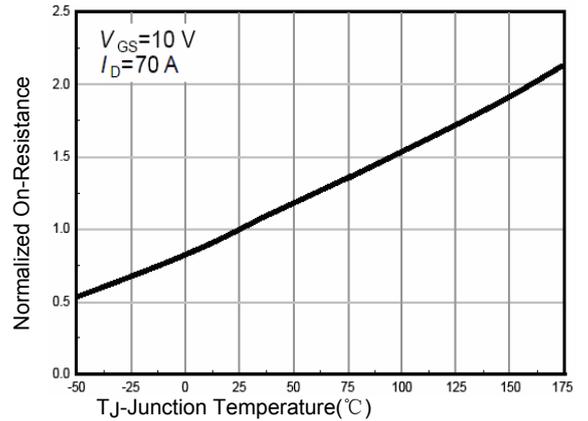
**Figure 1. Output Characteristics**



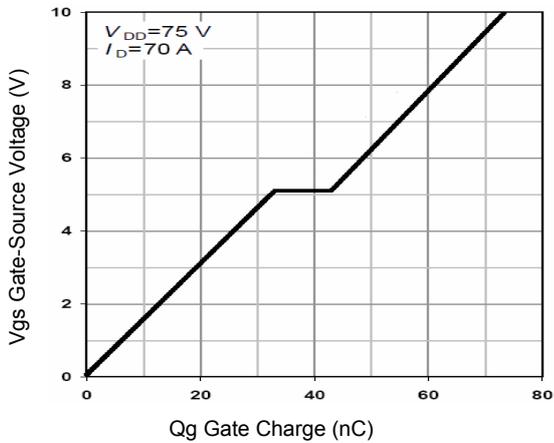
**Figure 2. Transfer Characteristics**



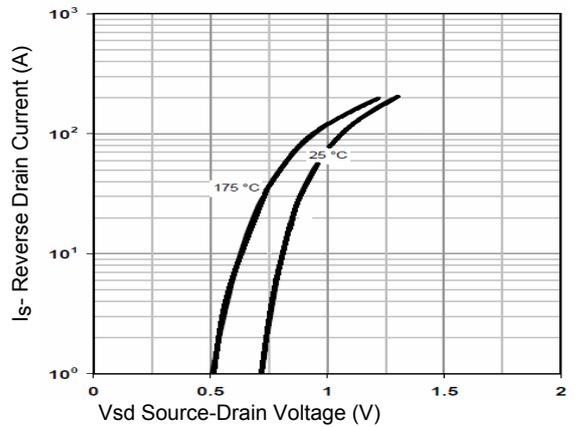
**Figure 3. Rdson- Drain Current**



**Figure 4. Rdson-Junction Temperature**

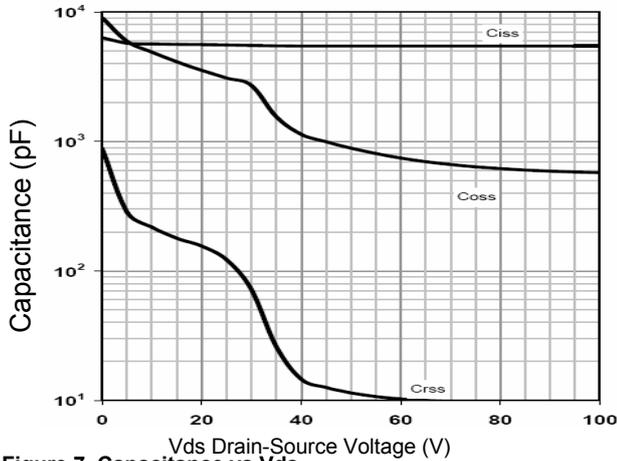


**Figure 5. Gate Charge**

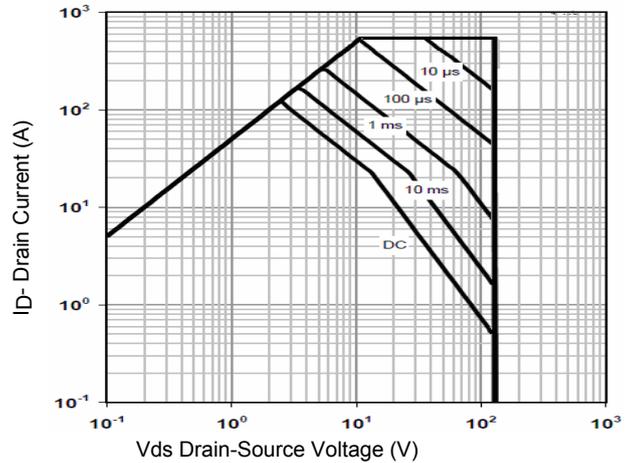


**Figure 6. Source- Drain Diode Forward**

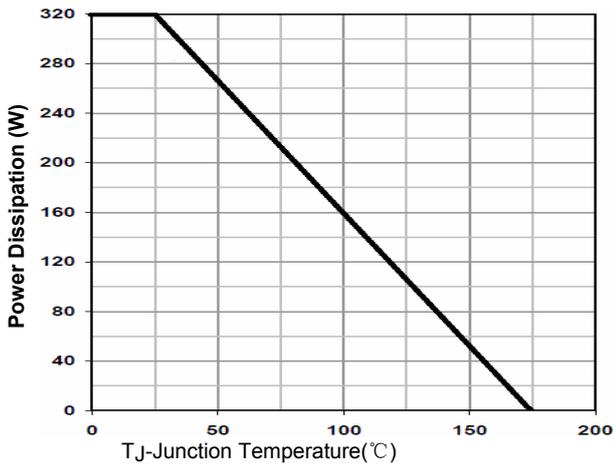
**Typical Electrical and Thermal Characteristic Curves**



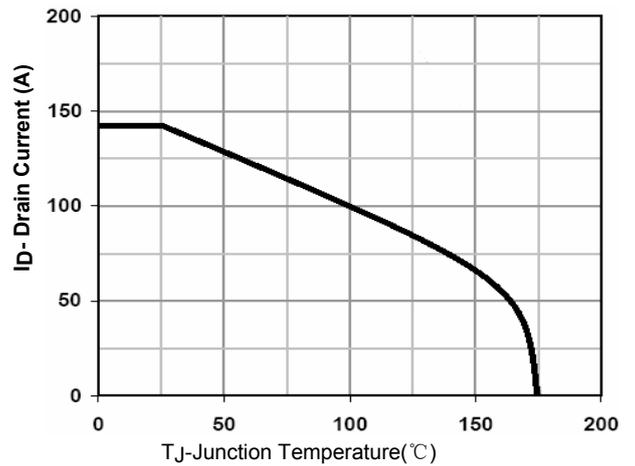
**Figure 7. Capacitance vs Vds**



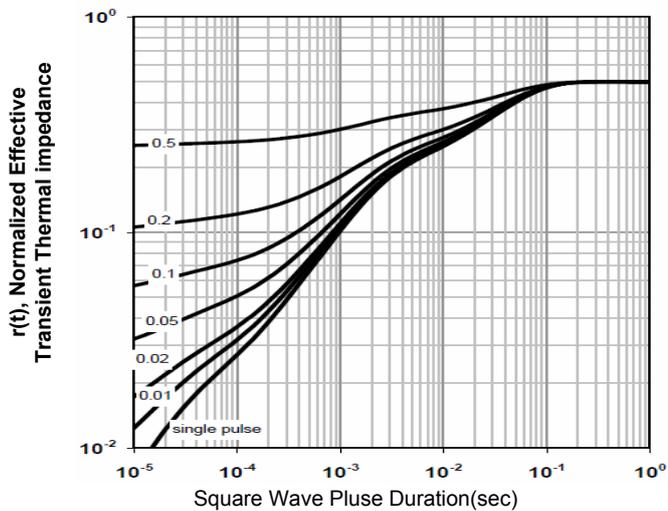
**Figure 8. Safe Operation Area**



**Figure 9. Power De-rating**



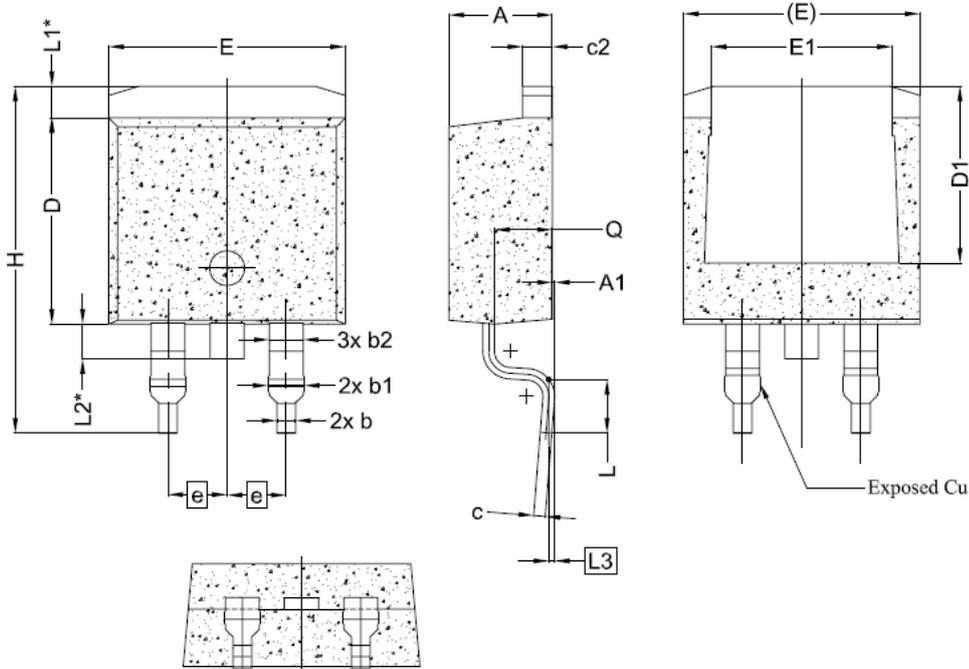
**Figure 10. Current De-rating**



**Figure 11. Normalized Maximum Transient Thermal Impedance**

**Package Outline Dimensions**

**TO-263 (D<sup>2</sup>PAK)**



| Symbol | Dimensions In Millimeters |       |       |
|--------|---------------------------|-------|-------|
|        | Min.                      | Nom.  | Max.  |
| A      | 4.24                      | 4.44  | 4.64  |
| A1     | 0.00                      | 0.10  | 0.25  |
| b      | 0.70                      | 0.80  | 0.90  |
| b1     | 1.20                      | 1.55  | 1.75  |
| b2     | 1.20                      | 1.45  | 1.70  |
| c      | 0.40                      | 0.50  | 0.60  |
| c2     | 1.15                      | 1.27  | 1.40  |
| D      | 8.82                      | 8.92  | 9.02  |
| D1     | 6.86                      | 7.65  | -     |
| E      | 9.96                      | 10.16 | 10.36 |
| E1     | 6.89                      | 7.77  | 7.89  |
| e      | 2.54BSC                   |       |       |
| H      | 14.61                     | 15.00 | 15.88 |
| L      | 1.78                      | 2.32  | 2.79  |
| L1     | 1.36 REF.                 |       |       |
| L2     | 1.50 REF.                 |       |       |
| L3     | 0.25 BSC                  |       |       |
| Q      | 2.30                      | 2.48  | 2.70  |